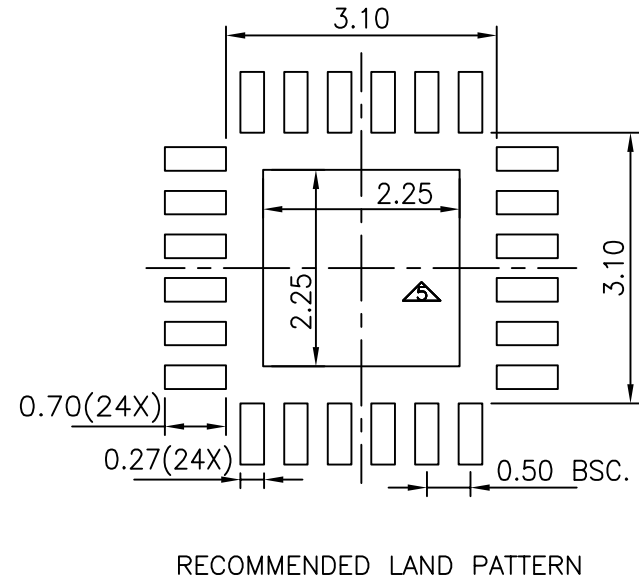
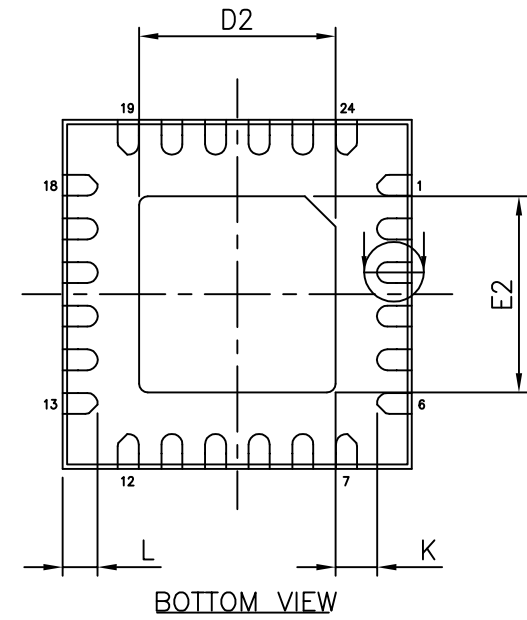
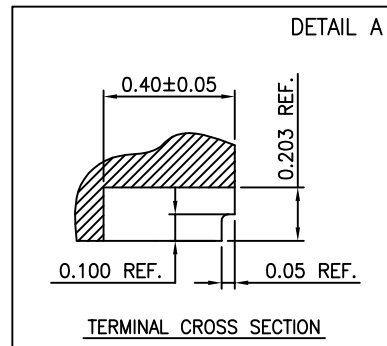
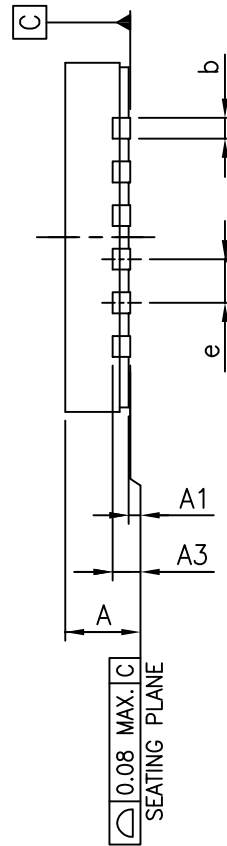


SYMBOLS	MIN.	NOM.	MAX.
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.18	0.25	0.30
D	3.90	4.00	4.10
E	3.90	4.00	4.10
e	0.50 BSC		
D2	2.20	2.25	2.30
E2	2.20	2.25	2.30
L	0.35	0.40	0.45



DATE: 04/20/22

DIODES **PERICOM** A PRODUCT LINE OF DIODES INCORPORATED
INCORPORATED ENABLING SERIAL CONNECTIVITY

DESCRIPTION: TQFN (V-QFN4040-24) (SWP)

PACKAGE CODE: ZDQ (ZDQ24)

DOCUMENT CONTROL #: PD-2236

REVISION: A

NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA